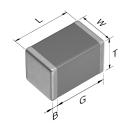
积层贴片陶瓷片式电容器

C2012CH1H222J060AA

RoHS Reach Halogen Free Pb Free

交货型号	C2012CH1H222JT****
用途	一般等级
特点	General 一般(~75V)
系列	C2012 [EIA 0805]
状态	▲ 量产体制(新设计非推荐)



尺寸			
长度(L)	$2.00 \text{mm} \pm 0.20 \text{mm}$		
宽度(W)	1.25mm ±0.20mm		
厚度(T)	0.60 mm ± 0.15 mm		
端子宽度(B)	0.20mm Min.		
端子间隔(G)	0.50mm Min.		
推荐焊盘布局(PA)	1.00mm to 1.30mm(Flow Soldering)		
1世存产益4月/月 (FA)	0.90mm to 1.20mm(Reflow Soldering)		
推荐焊盘布局(PB)	1.00mm to 1.20mm(Flow Soldering)		
TE存斥血和内(ID)	0.70mm to 0.90mm(Reflow Soldering)		
推荐焊盘布局(PC)	0.80mm to 1.10mm(Flow Soldering)		
TEAT/PETTIP PU (L C)	0.90mm to 1.20mm(Reflow Soldering)		

电·	气特性
电容	2. 2nF ±5%
额定电压	50VDC
温度特性	CH(0±60ppm/° C)
Q (Min.)	1000
绝缘电阻 (Min.)	10000M Ω

	其他	
焊接方法	流体	
件按月伝	回流	
AEC-Q200	NO	
包装形式	纸编带 (180mm卷筒)	
包装个数	4000pcs	

[!] Images are for reference only and show exemplary products.

[!] This PDF document was created based on the data listed on the TDK Corporation website.

[!] All specifications are subject to change without notice.

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特性图表(这是参考数据,并不保证产品的特性。)

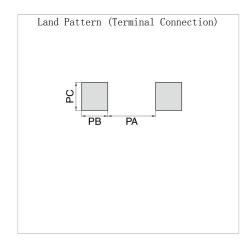
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Associated Images



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